

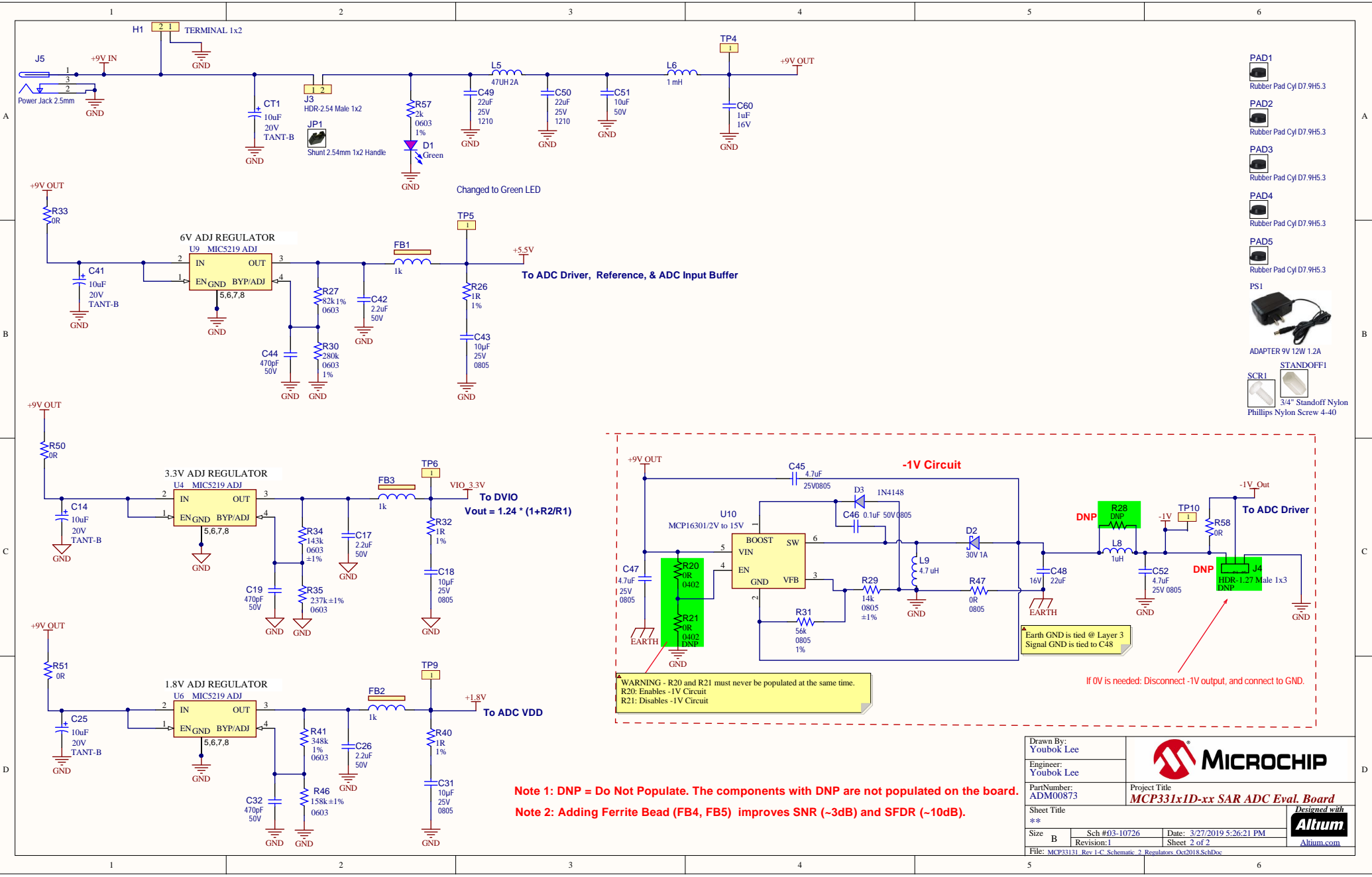


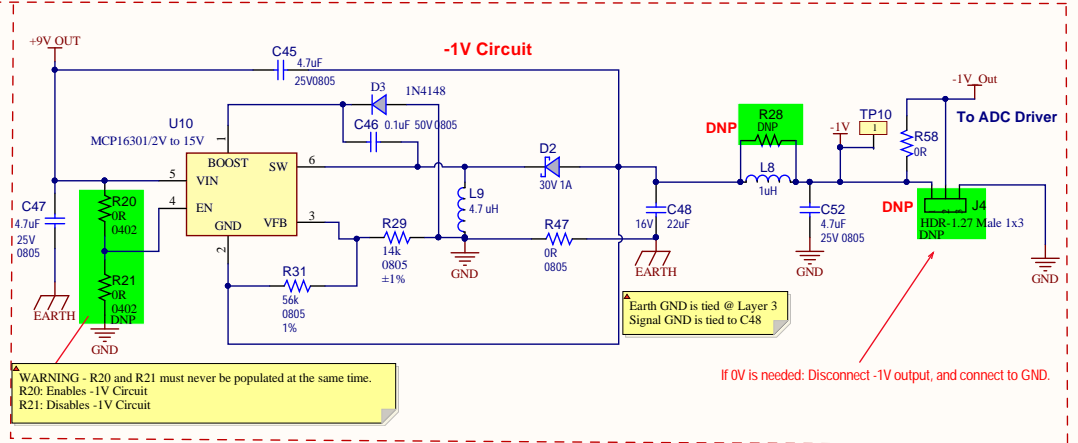
Drawn By: Youbok Lee		
Engineer: Youbok Lee		
PartNumber: ADM00873		Project Title MCP331xID-xx SAR ADC Eval Board
Sheet Title **		Date: 3/27/2019 5:26:20 PM Sheet 1 of 2
Size B	Sch #03-10726 Revision: 1	File: MCP331x Rev 1-C_Schematic_1 with 4V Reference_Oct2018.SchDoc



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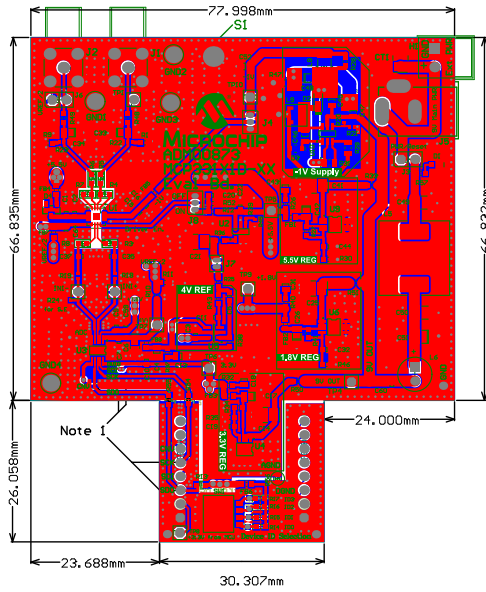


- PAD1 Rubber Pad Cyl D7.9H5.3
- PAD2 Rubber Pad Cyl D7.9H5.3
- PAD3 Rubber Pad Cyl D7.9H5.3
- PAD4 Rubber Pad Cyl D7.9H5.3
- PAD5 Rubber Pad Cyl D7.9H5.3
- PS1 ADAPTER 9V 12W 1.2A
- STANDOFF1 3/4" Standoff Nylon
- SCR1 Phillips Nylon Screw 4-40



Note 1: DNP = Do Not Populate. The components with DNP are not populated on the board.
Note 2: Adding Ferrite Bead (FB4, FB5) improves SNR (~3dB) and SFDR (~10dB).

Drawn By: Youbok Lee		
Engineer: Youbok Lee		
Part Number: ADM00873		Project Title: MCP331x1D-xx SAR ADC Eval Board
Sheet Title: **		Designed with:
Size: B	Sch #03-10726	Date: 3/27/2019 5:26:21 PM
Revision: 1		Sheet: 2 of 2
File: MCP331x1 Rev 1-C_Schematic_2_Regulators_Oct2018.SchDoc		



ASSEMBLY NOTES:
 1. ALL COMPONENTS SHALL BE RIGID COMPONENTS.
 2. ALL HOLE THROUGH HOLE COMPONENTS LOCATIONS SHALL BE FREE OF SOLDER.
 3. ALL COMPONENTS SHALL BE MOUNTED TO THE BOARD EXCEPT AS NOTED.
 4. FINISHED BOARD SHALL BE FREE OF ALL DEFECTS.
 5. ALL DIMENSIONS SHALL BE INDICATED TO THE CENTER UNLESS OTHERWISE NOTED.
 6. PLACE LABEL ON THE LOCATION INDICATED.
 7. SPECIFY THE DIMENSIONS ON THE FOLLOWING PAGE.
 8. SPECULATE GAIN (TOP) & STANDOFF (BOTTOM) AT MOUNTING POINT S1.

REV	ECD	Comments	Date

THIS PCB TO BE MANUFACTURED TO MEET ALL ACCEPTANCE LEVELS OF A CLASS 2 PCB PER ANSI/IPC-A-600G.

MATERIAL:

IPC 4101/126 or Equivalent

MULTILAYER 4 LAYERS CONTROLLED IMPEDANCE (50um +/-10%, See Note 1* for area)

Cu WEIGHT EXTERNAL LAYERS 1.5 OZ FINISHED

Cu WEIGHT INTERNAL LAYERS 2.0 OZ FINISHED

FINISHED OVERALL THICKNESS 0.064 mils mils + 5 %

COPPER THICKNESS ALLOWED YES NO

FINISH: LEAD-FREE HOT AIR LEVELING

IMERSION GOLD

IMERSION TIN

SMOBC WITH SELECTIVE GOLD PLATING ON LANDS INDICATED. Turn GOLD OVER 5-10 um NICKEL.

SOLDERMASK:

SOLDERMASK COLOR:

SILKSCREEN COLOR:

ALL HOLES TO BE LOCATED BY THE COORDINATES FROM THE NC DRILL DATA PROVIDED.

USE ARTWORK SET NO. PCB REV

ALL UL LOGO, MANUFACTURERS ID, AND DATE CODES SHALL BE PLACED ON THE BOTTOM SIDE UNLESS OTHERWISE INDICATED.

ANY ALTERNATIVES TO THE ABOVE SPECIFICATIONS MUST FIRST BE APPROVED.

REV	DATE	DESCRIPTION	BY	CHKD
1	3/27/2019	Initial Release	Y. Lee	

MICROCHIP

Microchip Technology Inc.
2355 W. Chandler Blvd.
Chandler, AZ 85224

TITLE: **MCP331x1D-xx SAR ADC Eval. Board**

PCB DESIGNER: **Y. Lee**

ENGINEER: **Y. Lee**

PCB FILE NAME: **ADM00873-RI-C_042018.PcbDoc**

PART NUMBER: **ADM00873**

GERBER FILE: **Multilayer Composite Print**

BOARD NUMBER: **04-10726**

DOCUMENT NUMBER: **02-10726**

DATE: **3/27/2019**

REV: **1**